

General Description

The MDP15N075 uses advanced MagnaChip's MV MOSFET Technology, which provides high performance in on-state resistance, fast switching performance, and excellent quality.

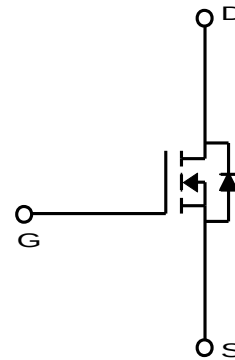
These devices can also be utilized in industrial applications such as Low Power Drives of E-bike (E-Vehicles), DC/DC converter, and general purpose applications.

Features

- $V_{DS} = 150V$
- $I_D = 120A$ @ $V_{GS} = 10V$
- Very low on-resistance $R_{DS(ON)} < 7.5 m\Omega$ @ $V_{GS} = 10V$
- 100% UIL Tested
- 100% Rg Tested



TO-220



Absolute Maximum Ratings ($T_a = 25^\circ C$)

Characteristics		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	150	V
Gate-Source Voltage		V_{GSS}	± 20	V
Continuous Drain Current ⁽¹⁾	$T_c = 25^\circ C$ (Silicon Limited)	I_D	144	A
	$T_c = 25^\circ C$ (Package Limited)		120	
	$T_c = 100^\circ C$		91	
Pulsed Drain Current ⁽³⁾		I_{DM}	480	
Power Dissipation	$T_c = 25^\circ C$	P_D	312	W
	$T_c = 100^\circ C$		125	
Single Pulse Avalanche Energy ⁽²⁾		E_{AS}	450	mJ
Junction and Storage Temperature Range		T_J, T_{stg}	-55~150	$^\circ C$

Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient ⁽¹⁾	$R_{\theta JA}$	62.5	$^\circ C/W$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.4	

Ordering Information

Part Number	Temp. Range	Package	Packing	RoHS Status
MDP15N075TH	-55~150°C	TO-220	Tube	Halogen Free

Electrical Characteristics (T_J =25°C)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V	150	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.1	-	4.1	
Drain Cut-Off Current	I _{DSS}	V _{DS} = 120V, V _{GS} = 0V	-	-	1.0	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±0.1	
Drain-Source ON Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 50A	-	6.2	7.5	mΩ
Forward Transconductance	g _{fs}	V _{DS} = 10V, I _D = 100A	-	70	-	S
Dynamic Characteristics						
Total Gate Charge	Q _g	V _{DS} = 50V, I _D = 50A, V _{GS} = 10V	-	91	-	nC
Gate-Source Charge	Q _{gs}		-	33	-	
Gate-Drain Charge	Q _{gd}		-	25	-	
Input Capacitance	C _{iss}	V _{DS} = 40V, V _{GS} = 0V, f = 1.0MHz	-	6,220	-	pF
Output Capacitance	C _{oss}		-	2,220	-	
Reverse Transfer Capacitance	C _{rss}		-	94	-	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DS} = 50V, I _D = 50A, R _G = 3.0Ω	-	40	-	ns
Rise Time	t _r		-	28	-	
Turn-Off Delay Time	t _{d(off)}		-	69	-	
Fall Time	t _f		-	20	-	
Gate Resistance	R _g	f=1 MHz	-	3	-	Ω
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	V _{SD}	I _S = 50A, V _{GS} = 0V	-	0.9	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 50A, dI/dt = 100A/μs	-	153	-	ns
Body Diode Reverse Recovery Charge	Q _{rr}		-	655	-	nC

Note :

1. Surface mounted FR-4 board by JEDEC (jesd51-7). Continuous current at T_c=25°C is silicon limited
2. E_{AS} is tested at starting T_j = 25°C, L = 1.0mH, I_{AS} = 30.0A, V_{GS} = 10V.
3. Pulse width limited by TJmax

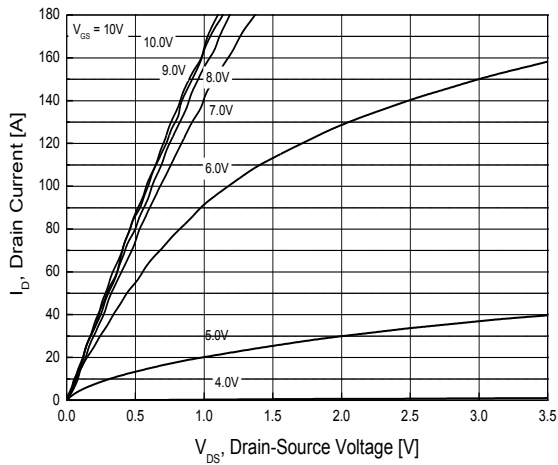


Fig.1 On-Region Characteristics

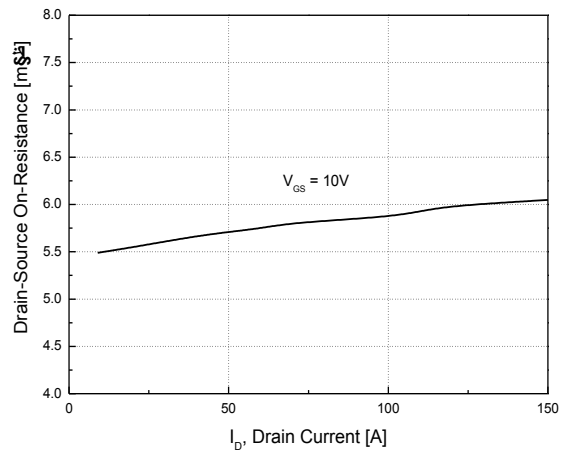


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

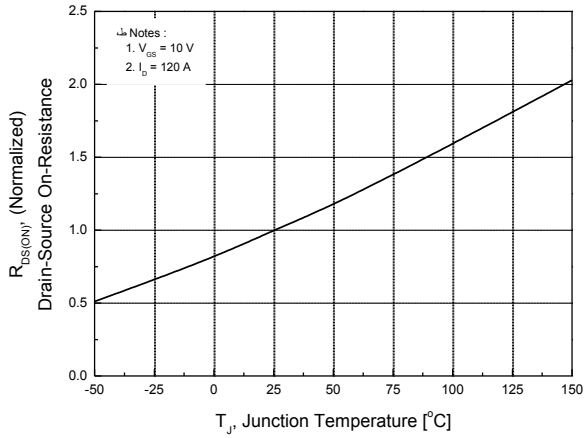


Fig.3 On-Resistance Variation with Temperature

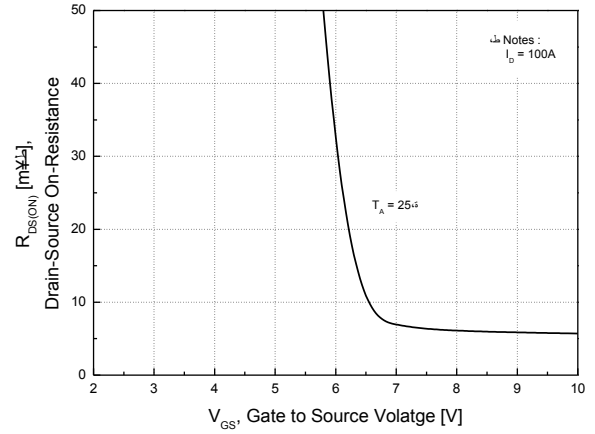


Fig.4 On-Resistance Variation with Gate to Source Voltage

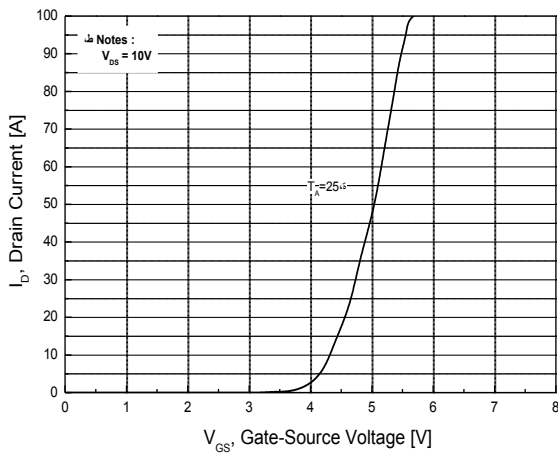


Fig.5 Transfer Characteristics

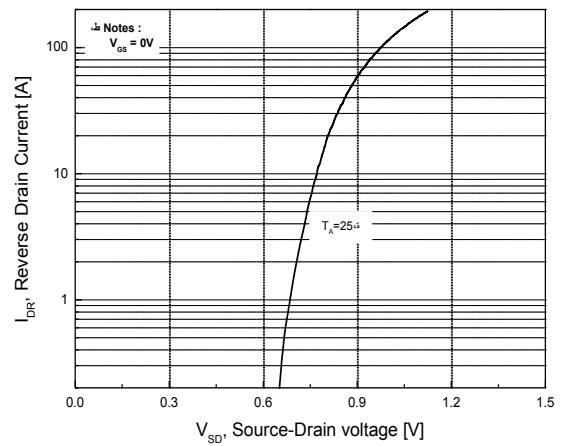
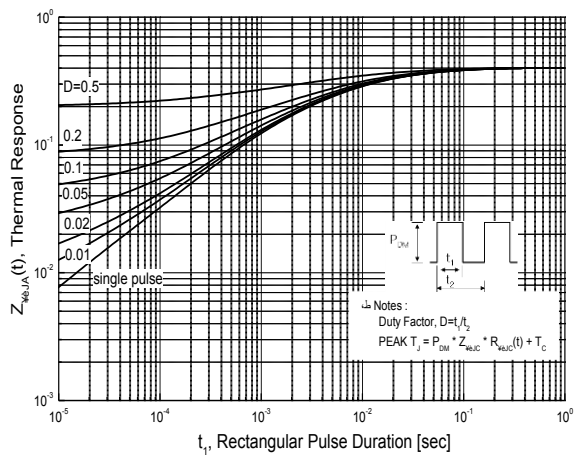
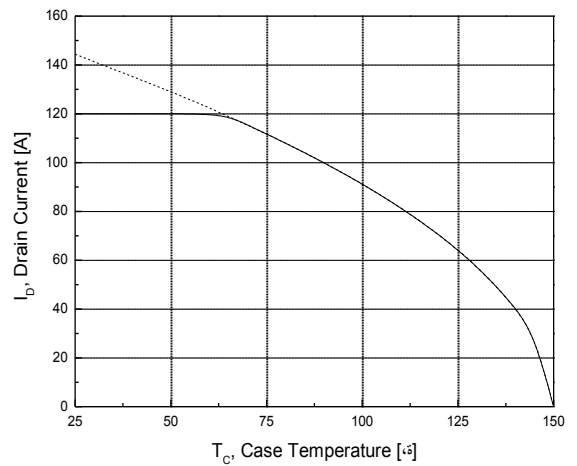
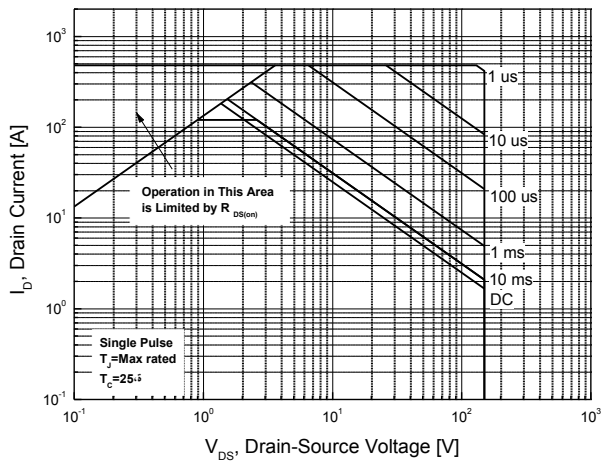
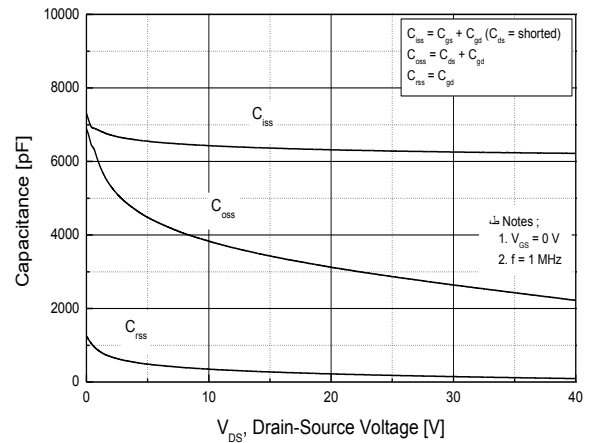
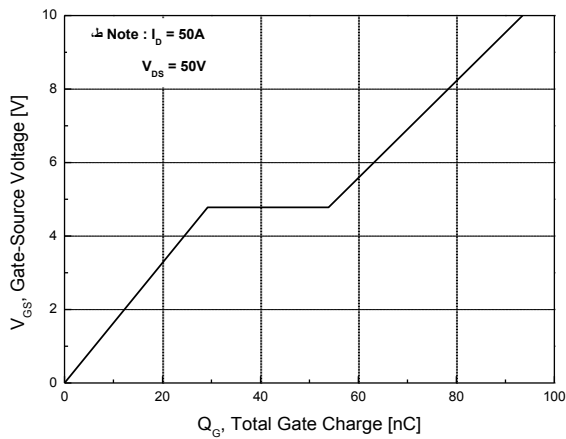
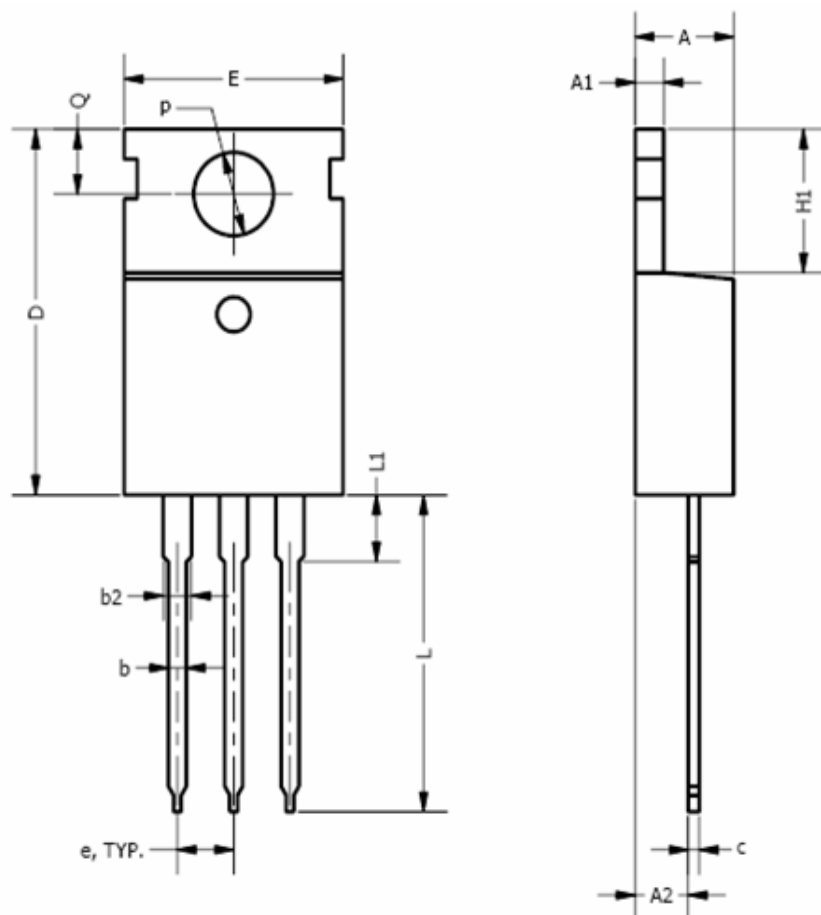


Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature



3 Leads, TO-220

Dimensions are in millimeters unless otherwise specified



Symbol	Min	Nom	Max
A	3.56		4.83
A1	0.50		1.40
A2	2.03		2.92
b	0.38	0.69	1.02
b2	1.14	1.45	1.78
c	0.36		0.61
D	14.22		16.51
e	2.54 TYP		
E	9.65		10.67
H1	5.84		6.86
L	12.70		14.73
L1			6.35
ϕP	3.53		4.09
Q	2.54		3.43

DISCLAIMER:

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